

IN THE SPECIFICATION:

Please replace the paragraph beginning on page 7, line 7 with the following:

In the present invention, it is important that the thickness of surface oxide of metal is at least 0Å and less than 50Å. The thickness is preferably at least 25Å and 50Å, and further preferably 30Å and less than 40Å. The ~~Thinner~~ thinner the surface oxide is, the more preferable it is, because the etching rate becomes faster.

However, when the surface oxide is thinner than 25Å, a heat resistance thereof deteriorates, and when the surface oxide is exposed to a high temperature of 200°C or higher, a discoloration may occur, to which attention should be paid. Further, since the etching rate of the insulating layer varies due to variations in thickness of the surface oxide, it is preferable that the thickness of the surface oxide is constant. On the other hand, when the thickness of the surface oxide is 50Å or more, such a drawback occurs that the etching rate of the insulating layer becomes considerably slow and a productivity is much deteriorated, which is undesirable. Further, since the etching rate is ~~fast~~ slow, the so-called over-etching phenomenon is easy to occur, which makes it impossible to conduct micro-fabrication, for example, fabrication of a line-shape with a width of 30μm. As a result, it becomes difficult to meet size reduction of a suspension required for micro-fabrication, which is not desirable.

Please replace the paragraph beginning at page 10, line 1 with the following:

The thermoplastic resin used in the insulating layer in the metal laminate of the present invention is not limited to a specific one. However, it is preferable that the thermoplastic resin is thermoplastic polyimide obtained by polymerizing at least

one diamine selected from the group consisting of 1,3-bis (3-aminophenoxy) benzene, 1,3-bis (3- (3-aminophenoxy) phenoxy) benzene, 4, 4'-bis (3-aminophenoxy) biphenyl and ~~3, 3'-diaminobenzophenone~~ 3, 3'-diaminobenzophenone, and at least one tetra-carboxylic dianhydride selected from the group consisting of pyromellitic dianhydride, ~~3, 3', 4, 4'-biphenyl-tetra-carboxylic dianhydride~~, ~~3, 3', 4, 4'-benzophenone tetra-carboxylic dianhydride~~, or ~~3, 3', 4, 4'-diphenyl-ether-tetra-carboxylic dianhydride~~ 3, 3', 4, 4'-biphenyl-tetra-carboxylic dianhydride, 3, 3', 4, 4'-benzophenone tetra-carboxylic dianhydride, or 3, 3', 4, 4'-diphenyl-ether-tetra-carboxylic dianhydride.

Please replace the paragraph beginning at page 15, line 11 with the following:

First, a photosensitive resin is formed on a metal surface of the metal laminate plate of the present invention for forming a circuit by application or pasting. A mask on which a desired pattern image has been drawn is brought in close contact with the photosensitive resin and microwaves with a wavelength where the photosensitive resin has sensitivity are irradiated on the photosensitive resin. A non-exposed portion of the photosensitive resin is eluted with predetermined developer to form a desired circuit image on the metal. After exposed metal has been ~~solved~~ dissolved by dipping the metal laminate in this state in solution which can ~~solve~~ dissolve metal such as ferric chloride or the like or spraying the solution on the substrate, the photosensitive resin is released by a predetermined releasing agent to form the circuit.